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Dr. Rhee Min Woo is Master and Vice President of Technology and leading Advanced Packaging Technology Development in Semiconductor R&D in Samsung Electronics. He received the B.Eng., M.S. and Ph.D. degrees in chemical engineering from Sogang University, Seoul, in 1996, 1998, and 2010, respectively and Master's degree of Industrial systems Engineering & Management from National University of Singapore (NUS) in 2017. He has been working for more than 25 years in microelectronics packaging R&D for both industry and research institutes with extensive experience in advanced packaging architecture, process, material, numerical modeling and characterization. From 1999 to 2011, he was with R&D at Amkor Technology as a senior manager and also he was a principal engineer in Package R&D group at Fairchild Semiconductor, where he developed high power inverter module for automotive application. From 2011 to 2015, he was the head of department at Institute of Microelectronics (IME-A*STAR), Singapore and led the advanced packaging group and related industry consortium projects such as Fan-out, MEMS, 3DIC TSV. He authored and co-authored about 100 journal and conference papers and over 30 patents in microelectronics and advanced packaging fields. He is currently serving as a technical committee of Packaging Technologies in IEEE EPS (Electronic Packaging Society) ECTC (Electronic Component of Technology Conference) and Co-Chair of Advanced Packaging Technical Committee in IEEE EPTC (Electronic Packaging Technology Conference).